



Low VF Glass Passivated Bridge Rectifiers

Reverse Voltage - 600 Volts
Forward Current - 2.0 Amperes

Features

- Glass passivated chip
- Low forward voltage drop
- Ideal for printed circuit board
- High surge current capability
- Meet UL flammability classification 94V-0

Mechanical Data

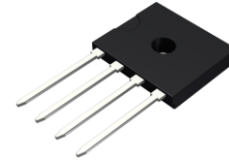
- Polarity: Symbol marked on body
- Mounting position: Any

Note: Products with logo  or  are made by HY Electronic (Cayman) Limited.

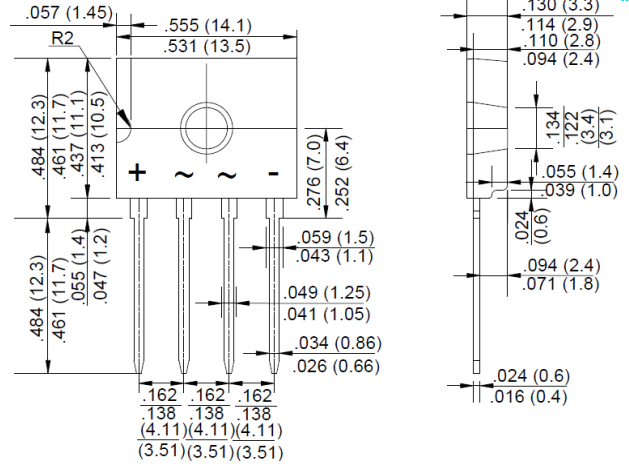
Applications

- General purpose use in AC/DC bridge full wave rectification, for SMPS, lighting ballaster, adapter, etc.

D3K



RoHS COMPLIANT



Package Outline Dimensions in Inches (Millimeters)

Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.
 Single phase, half wave, 60Hz, resistive or inductive load.
 For capacitive load, derate current by 20%.

Characteristics	Symbol	D2KB6F	Unit
Maximum Repetitive Peak Reverse Voltage	VRRM	600	V
Maximum RMS Voltage	VRMS	420	V
Maximum DC Blocking Voltage	VDC	600	V
Maximum Average Forward Rectified Current @Tc=138°C	I(AV)	2	A
Peak Forward Surge Current, 8.3mS Single Half Sine-Wave, Superimposed on Rated Load (JEDEC Method)	IFSM	65	A
I ² t Rating for Fusing (t<8.3mS)	I ² t	17.5	A ² s
Peak Forward Voltage per Diode at 2.0A DC	VF	0.95	V
Typical Thermal Resistance to Ambient (without heatsink)	RθJA	55	°C/W
Typical Thermal Resistance to case (with heatsink (Note2))	RθJC	1.5	°C/W
Typical Thermal Resistance to lead (without heatsink)	RθJL	15	°C/W
Maximum DC Reverse Current at Rated @Tj=25°C	IR	5	μA
DC Bolcking Voltage per Diode @Tj=125°C		500	
Operating Junction Temperature Range	TJ	-55 to +150	°C
Storage Temperature Range	TSTG	-55 to +150	°C

Notes: 1. Device mounted on 50mm*50mm*1.6mm Cu plate heatsink.

2.The typical data above is for reference only



Fig. 1 - Forward Current Derating Curve

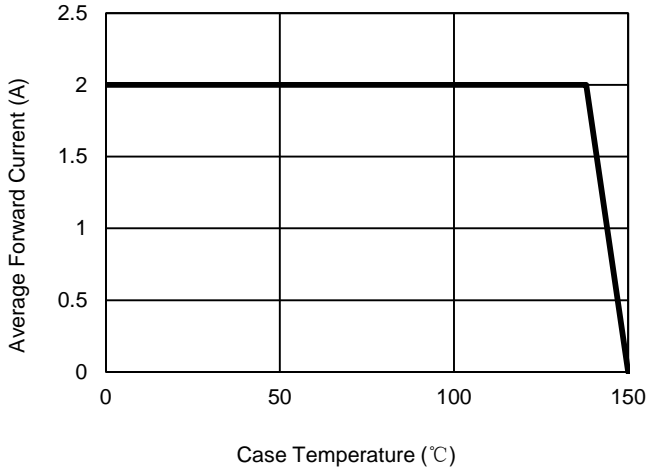


Fig. 2 - Maximum Non-Repetitive Surge Current

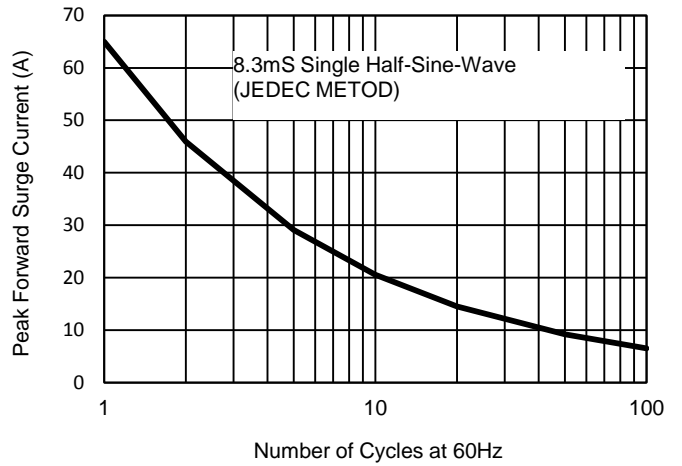


Fig. 3 - Typical Reverse Characteristics

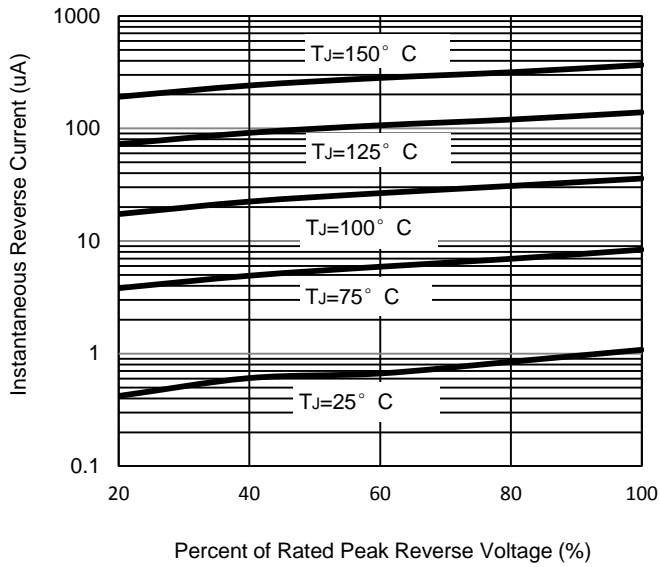
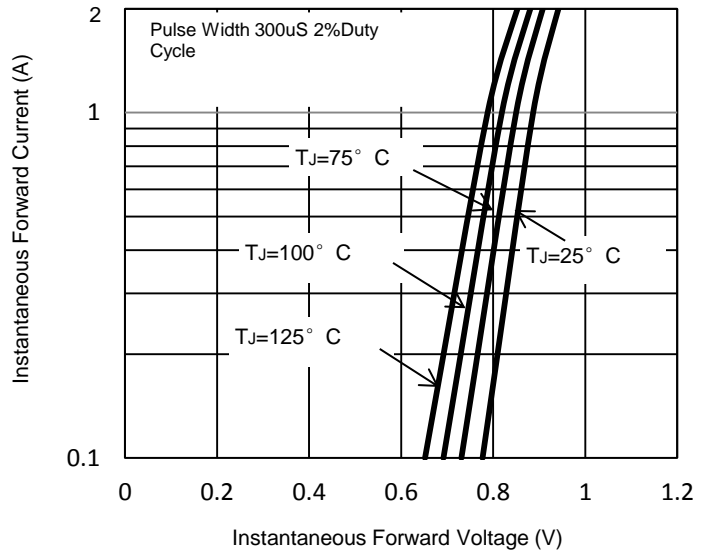


Fig. 4 - Typical Forward Characteristics





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